

CLAIMS

We claim:

1. An integrated circuit ("IC") layout comprising a first set of vias that have a diamond shape and a second set of vias that have a rectangular shape.
2. The IC layout of claim 1, wherein a first via in the first set traverses two layers of the IC layout and the first via has a contact on each of the layers, wherein each contact is in shape of a diamond.
3. The IC layout of claim 2, wherein a second via in the second set traverses two layers of the IC layout and the second via has a contact on each of the layers, wherein each contact of the second via is in shape of a rectangle.
4. An integrated-circuit ("IC") layout comprising a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of the layers, wherein one of the contacts is in shape of a rectangle and one of the contacts is in shape of a diamond.
5. The IC layout of claim 4, wherein the rectangle is a square.
6. The IC layout of claim 4, wherein the rectangle has different length and width.
7. The IC layout of claim 4, wherein the diamond has four equal sides.
8. The IC layout of claim 4, wherein the diamond has two pairs of sides, wherein the length of one pair of sides is different than the length of the other pair of sides.

9. An integrated-circuit ("IC") layout comprising a first set of vias, wherein each via in the first set traverses at least two layers and has one contact on each of the layers, wherein one of the contacts is in ^{the} shape of a quadrilateral polygon and one of the contacts is in shape of a non-quadrilateral polygon.

Patent Application No. 10/000,000